

File 342:Derwent Patents Citation Indx 1978-98/200004

?s PN=US 4999160

S2 1 PN=US 4999160

?map cgpn temp

1 Select Statement(s), 10 Search Term(s)

Serial#TD034

File 350:DERWENT WPIX 1963-2000/UD=, UM=, & UP=200020

Executing TD034

S1 9 PN=EP 573002 + PN=EP 582605 + PN=US 5376235 + PN=US
5443995 + PN=US 5747360 + PN=US 5814557 + PN=US 5843842 +
PN=US 5846877 + PN=US 5904562 + PN=WO 9220099
S2 2 S1 AND INTERCONNECT?
S4 23 (TITANIUM AND ALUMINUM AND COPPER AND INTERCONNECT?)
S5 10 TITANIUM AND ALUMINUM AND COPPER AND ELECTROMIGR?
S6 2 S5 NOT S4
S7 4065 VLSI OR ULSI
S9 11534 (AL OR ALUMINUM) AND (CU OR COPPER) AND (TI OR TITANIUM)
S10 19 S7 AND S9
S11 17 S10 NOT S4 NOT S6

(No additional references)

File 348:European Patents 1978-2000/Apr W03

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*File 348: ** NEW FEATURE ** English language translations of French and German abstracts now searchable. See HELP NEWS 348 for info.

File 349:PCT Fulltext 1983-2000/UB=, UT=20000406

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Set Items Description

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?DS

Set	Items	Description
S1	13749	AL-ALLOY? OR ALUMINUM (N7)ALLOY?
S2	102006	TITANIUM OR TI
S3	99601	COPPER OR CU
S4	99367	INTERCONNECT?
S5	4161	S1 AND S2 AND S3
S6	844	S5 AND S4
S7	924	ELECTRO-MIGRATION? OR ELECTROMIGRATION? OR ELECTRO()MIGRAT- ION? OR STRESS-MIGRATION?
S8	89	STRESS(W)MIGRATION?
S9	0	S7 AND S89
S10	924	S7 OR S89
S11	941	S7 OR S8
S12	148	S6 AND S11
S13	1112	S1 (10N) S2 (10N) S3
S14	53	S4 (50N) S13
S15	20	S14 AND S11

4,5,8,18

?t /ti,pn/4,5,8,12,18,20

15/TI,PN/4 (Item 4 from file: 348)

DIALOG(R)File 348:(c) 2000 European Patent Office. All rts. reserv.

ORDER fax of complete patent from Dialog SourceOne. See HELP ORDER 348
Semiconductor device having aluminum contacts or vias and method of
manufacture therefor

PATENT (CC, No, Kind, Date): EP 866498 A2 980923 (Basic)
EP 866498 A3 990707

15/TI,PN/5 (Item 5 from file: 348)

DIALOG(R)File 348:(c) 2000 European Patent Office. All rts. reserv.

Aluminum interconnections

PATENT (CC, No, Kind, Date): EP 813245 A2 971217 (Basic)
EP 813245 A3 000105

15/TI,PN/8 (Item 8 from file: 348)

DIALOG(R)File 348:(c) 2000 European Patent Office. All rts. reserv.

STABILIZATION OF THE INTERFACE BETWEEN ALUMINUM AND TITANIUM NITRIDE

PATENT (CC, No, Kind, Date): EP 582605 A1 940216 (Basic)
EP 582605 B1 990721
WO 9220099 921112

15/TI,PN/12 (Item 12 from file: 348)

DIALOG(R)File 348:(c) 2000 European Patent Office. All rts. reserv.

Transition metal clad interconnect for integrated circuits.

PATENT (CC, No, Kind, Date): EP 273629 A2 880706 (Basic)
EP 273629 A3 880921

15/TI,PN/18 (Item 5 from file: 349)

DIALOG(R)File 349:(c) 2000 WIPO/MicroPatent. All rts. reserv.

A NOVEL VIA HOLE PROFILE AND METHOD OF FABRICATION

Patent and Priority Information (Country, Number, Date):
Patent: WO 9612295 A1 19960425

15/TI,PN/20 (Item 7 from file: 349)

DIALOG(R)File 349:(c) 2000 WIPO/MicroPatent. All rts. reserv.

STABILIZATION OF THE INTERFACE BETWEEN ALUMINUM AND TITANIUM NITRIDE

Patent and Priority Information (Country, Number, Date):
Patent: WO 9220099 A1 19921112